

MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

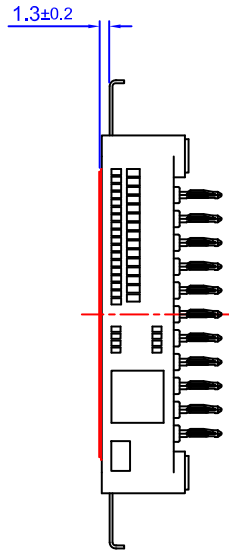
ON Semiconductor®



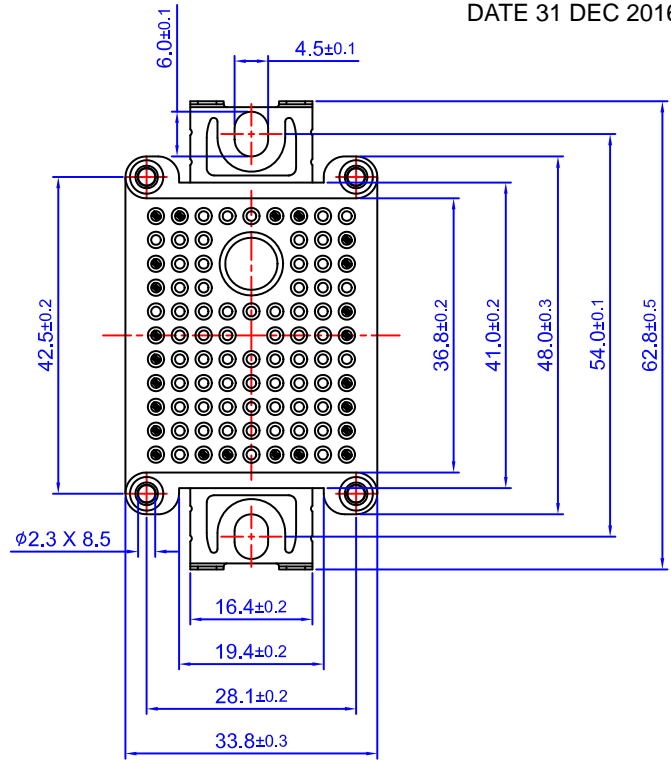
HF1CA-P24 / 24LD, HPM, F1 PKG, PRESSFIT TERMINAL, DC-DC MODULE

CASE MODCL
ISSUE O

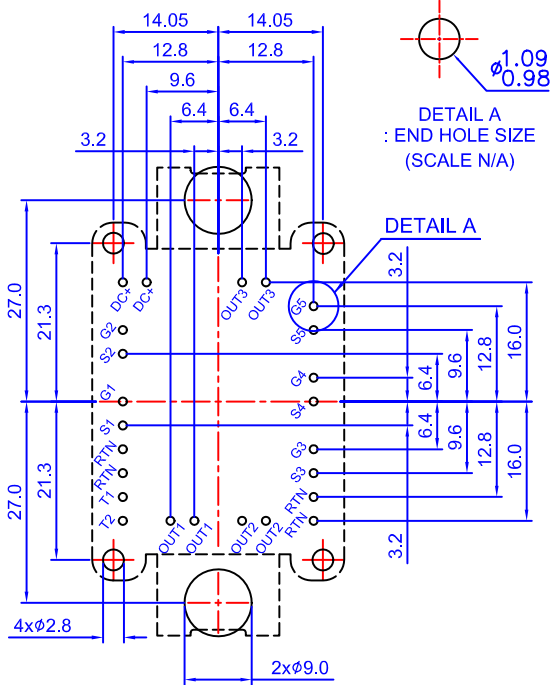
DATE 31 DEC 2016



SIDE VIEW



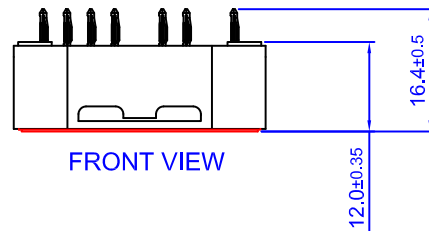
TOP VIEW



PCB HOLE PATTERN RECOMMENDATION

- PIN-GRID 3.2mm

- TOLERANCE OF PCB HOLE PATTERN $\varnothing \pm 0.1$



FRONT VIEW

- NOTES: UNLESS OTHERWISE SPECIFIED
- A) THIS PACKAGE DOES NOT COMPLY TO ANY CURRENT PACKAGING STANDARD
 - B) ALL DIMENSIONS ARE IN MILLIMETERS
 - C) DCDC MODULE TYPE

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STATUS:	ON SEMICONDUCTOR STANDARD	
NEW STANDARD:		
DESCRIPTION:	HF1CA-P24 / 24LD, HPM, F1 PKG, PRESSFIT TERMINAL	PAGE 1 OF 2

